TECHNICAL DATA DATA SHEET 994, REV. B Formerly part number SHDG1024

600 VOLT, 40 AMP IGBT DEVICE HIGH SPEED, IMPROVED SCSOA WITH FAST REVERSE RECOVERY DIODE

ELECTRICAL CHARACTERISTICS

(Tj=25°C UNLESS OTHERWISE SPECIFIED)

| ELECTRICAL CHARACTERISTICS | (1)- | 20 C OINL | L00 0111 | LIVVIOL 3 | LCII ILD) |
|--|--------------------------------------|-----------|------------|-----------|-----------|
| PARAMETER | SYMBOL | MIN | TYP | MAX | UNIT |
| IGBT SPECIFICATIONS | | | | | |
| Collector to Emitter Breakdown Voltage | BV _{CES} | 600 | - | - | V |
| $I_C = 250 \mu A, V_{GE} = 0V$ | | | | | |
| Continuous Collector Current $T_C = 25$ $^{\circ}$ C | I _C | - | - | 40 (1) | Α |
| $T_C = 90$ $^{\circ}C$ | | | | 40 | |
| Pulsed Collector Current, 1mS | I _{CM} | - | - | 130 | Α |
| Short Circuit time, $V_{GE} = 15V$, $V_{CE} = 500V$, $T_j = 125$ $^{\circ}C$ | t _{sc} | - | - | 10 | μsec |
| di/dt < 300 A/μsec, I _C < 300A | | | | | · |
| Gate to Emitter Voltage | V _{GE} | - | - | +/-20 | V |
| Gate-Emitter Leakage Current, V _{GE} = +/-20V | I _{GES} | - | - | +/- 100 | nA |
| Gate Threshold Voltage, I _C =2mA | V _{GE(TH)} | 4.0 | - | 7.0 | V |
| Zero Gate Voltage Collector Current | I _{CES} | | | | |
| $V_{CE} = 600 \text{ V}, V_{GE} = 0V T_{i} = 25^{\circ}\text{C}$ | | - | - | 0.25 | Ма |
| $V_{CE} = 480 \text{ V}, V_{GE} = 0V T_{i} = 125^{\circ}\text{C}$ | | - | - | 3.0 | mA |
| Collector to Emitter Saturation Voltage, $T_C = 25$ °C | V _{CE(SAT)} | - | 2.0 | 2.3 | V |
| $I_C = 40A, V_{GE} = 15V,$ $T_C = 125 {}^{\circ}C$ | | | 2.3 | 2.5 | |
| Input Capacitance | C _{ies} | - | 2800 | - | pF |
| Output Capacitance Reverse Transfer Cap. | C _{oes} C _{res} | | 300 200 | | |
| $V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 1 \text{ MHz}$ | O res | | 200 | | |
| Turn On Delay Time | t _{d(on)} | - | 100 | - | |
| Rise Time | t _r | _ | 50 | - | nsec |
| Turn Off Delay Time Fall Time | t _{d(off)} | _ | 300 40 | _ | 11000 |
| Turn off Energy Loss | t _f | | 40 | | |
| $(T_j = 125 ^{\circ}\text{C}, I_C = 40\text{A}, V_{GE} = 15\text{V}, \text{inductive load}, V_{CC} = 100 ^{\circ}\text{C}$ | E _{off} | _ | 1.5 | _ | mJ |
| 300 V, $R_G = 22 \Omega$ | E _{on} | - | 2.0 | - | mJ |
| Maximum Thermal Resistance | $R_{	heta JC}$ | - | - | 0.60 | °C/W |
| | 1 | | | | |

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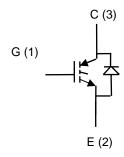
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ULTRAFAST DIODE RATING AND CHARACTERISTICS

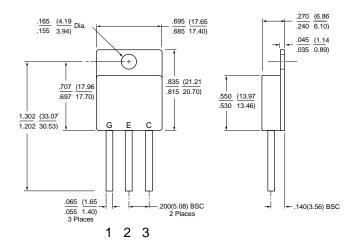
| PARAMETER | SYMBOL | MIN | TYP | MAX | UNIT |
|--|-------------------|-----|-----|--|------|
| Diode Peak Inverse Voltage | PIV | 600 | - | - | V |
| Continuous Forward Current, $T_C = 25$ °C $T_C = 90$ °C | I _F | - | - | 40 ⁽²⁾ 40 ⁽³⁾ | А |
| Forward Surge Current, t _p = 10 msec | I _{FSM} | - | - | 300 | Α |
| Diode Forward Voltage, $I_F = 40A$ | V _F | - | 1.5 | 1.8 | V |
| Diode Reverse Recovery Time | t _{rr} | - | 160 | 180 | nsec |
| Diode Reverse Recovery Charge (I _F =30A, V _{RR} =200V, di/dt=200 A/μs) | Q _{rr} | | | 1.2 | μС |
| Maximum Thermal Resistance | R ₀ JC | - | - | 0.85 | °C/W |
| Maximum and Storage Junction Temperature | T _{jmax} | -55 | - | 150 | °C |

- (1) Current is limited by package leads. Die current rating is 65A.
- (2) Current is limited by package leads. Die current rating is 75A.
- (3) Current is limited by package leads. Die current rating is 50A.

Schematic Diagram:



Package Drawing: (TO258)



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